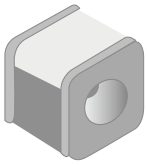
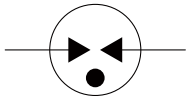
FEATURES

- Surface Mounting Design 5.5*4.2*4.2mm
- High Current Handling Capability 3,000A @ 8/20 μs
- Low Capacitance and Insertion Loss
- Quick Response and Long Service Life
- Moisture sensitivity level：Level 1



5.5*4.2*4.2mm



Schematic Symbol

APPLICATION INFORMATION

- Communication equipment.
- Repeaters,Modems
- Telephone Interface,Line cards.
- Data communication equipment.

AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
Pb	Mean lead free

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

ELECTRICAL PARAMETER

Parameter	Condition	Rating	Unit
DC Blocking Voltage 1)	100V/s	2880-4320	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ⩽ 5000	V
	At 1kV/μs	Typical values of distribution ⩽ 4800	V
Impulse Discharge Current 2)	8/20μs	3000	A
AC Discharge Current	50Hz, 1S, 10times	5	A
Insulation Resistance	DC=100V	⩾ 1	GΩ
Capacitance at 1MHz	V_{DC}=0.5V	⩽ 0.6	pF
Operating and Storage Temperature		-40-125	°C

1) In ionized mode
2) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

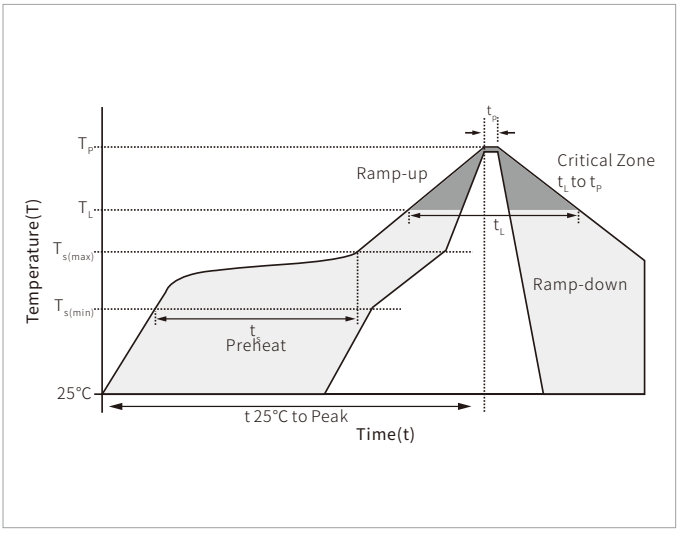
ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85°C ; Time:2H
Low Temperature Storage Test	Temperature: -40°C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude：0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering：10s，1time

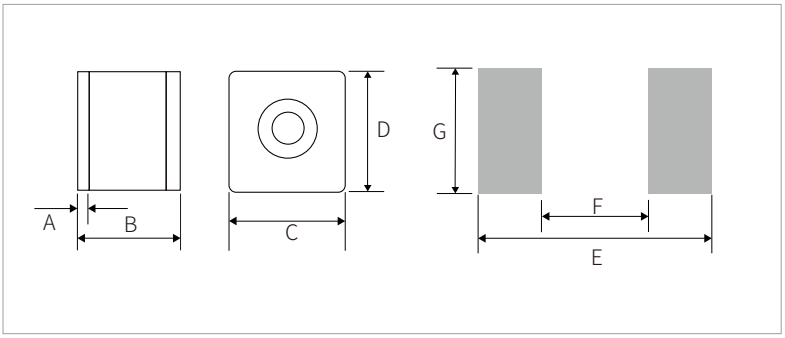
NOTE: Up-screen program can be specified by customer' s request via contacting Semiware service

REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60 – 180 secs
Average ramp up rate (Liquidus)Temp (T_L) to peak		3°C/second max
$T_{S(max)}$ to T_L - Ramp-up Rate		
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time(min to max)(t_S)	60 – 150 seconds
Peak Temperature (T_P)		260 °C
Time within 5°C of actual peak Temperature (tp)		20-40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		260°C

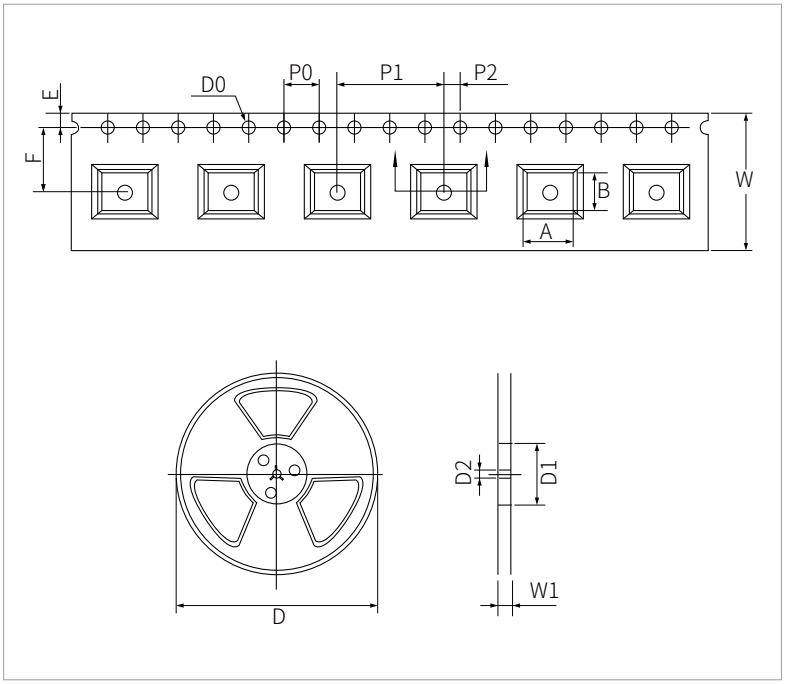


DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	mm
A	0.45±0.1
B	5.5±0.2
C	4.2±0.2
D	4.2±0.2
E	6.1
F	4.4
G	4.2

PACKAGE REEL INFORMATION



Ref.	mm	inch
A	4.5±0.1	0.177±0.004
B	5.8±0.1	0.228±0.004
D0	Φ 1.5±0.2	Φ 0.059±0.008
P0	4.0±0.2	0.157±0.008
P1	8.0±0.5	0.472±0.020
P2	2.0±0.2	0.079±0.008
E	1.75±0.2	0.069±0.008
F	7.5±0.2	0.295±0.008
W	16.0±0.5	0.630±0.020
D	Φ 330.0±2	Φ 12.99±0.079
D1	Φ 100+1/-2	$\Phi\ 3.94^{+0.039}_{-0.078}$
D2	Φ 13±0.15	0.512±0.006
W1	20±1	0.787±0.039

ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG5542B3600	5.5*4.2*4.2mm	1600	Box

Headquarters
No.3387 Shendu Road
Pujiang I&E Park
Minhang Shanghai China
201000

Hotline
400-021-5756

Web
Https://www.semiware.com

Sales Center
Tel: 86-21-3463-7458
Email: sales18@semiware.com

Customer Service
Tel: 86-21-5484-1001
Email: sales17@semiware.com

Technical Support
Tel: 86-21-3463-7654
Email: fae01@semiware.com

Complaint & Suggestions
Tel: 86-21-3463-7172
Ext: 8868
Email: cs03@semiware.com

By QR Code
Website
Wechat

To find your local partner within Semiware' s global website: www.semiware.com